

Amendments to the Claims:

This listing of claims replaces all prior versions and listings of claims in the application:

Listing of Claims:

1.-9. (cancelled)

10. (new) A method for patterning a surface of a substrate, the method comprising, in this order:

providing on the surface of a substrate, to form a photosensitive composition layer, a photosensitive composition for sandblasting comprising the following components (a), (b), (c) and (d):

(a) a photopolymerizable urethane (meth) acrylate oligomer comprising a reaction product of a compound having a terminal isocyanate group and a (meth) acrylate compound, wherein the compound having a terminal isocyanate group is obtained by reacting (poly) alkylene glycol with a diisocyanate compound, and the (meth) acrylate compound has a substituent selected from the group consisting of a hydroxyl group and a carboxyl group, said component (a) comprising 50% by weight or more of urethane (meth) acrylate oligomer comprising polyether structural units in a main chain;

(b) an acrylic copolymer having an acid value of from 50 mgKOH/g to 250 mgKOH/g and comprising, as a monomer unit, a copolymerizable monomer selected from the group consisting of a monomer with at least a benzene ring and a monomer with at least a cyclohexyl group, said component (b) comprising from 2% to 70% by weight of the copolymerizable monomer;

(c) a photopolymerization initiator; and

(d) a photopolymerizable monomer selected from the group consisting of diacrylates and dimethacrylates of polyethylene glycol and diacrylates and dimethacrylates of polypropylene glycol,

wherein the photosensitive composition has from 10 to 90 parts by weight of the component (a); from 10 to 90 parts by weight of the component (b); from 0.1 to 25 parts by weight of the component (c), based on the total amount of the components (a), (b) and (c), and

further wherein component (d) is present in an amount of no more than 20 parts by weight based on 100 parts by weight of the total amount of components (a), (b) and (c);

providing a mask pattern on the photosensitive composition layer;  
irradiating the photosensitive layer on which the mask pattern is provided with a light;  
removing the mask pattern from the photosensitive composition layer;  
carrying out a development to dissolve away unexposed areas of the photosensitive composition layer; and  
sandblasting the substrate.